



Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
USPTO Use Only

EFS ID: 59457  
Application ID: 10761122  
Title of Invention: SOLVENT FREE PHOTORESIST  
STRIP AND RESIDUE REMOVAL  
PROCESSING FOR POST ETCHING  
OF LOW-K FILMS  
First Named Inventor: HUONG NGUYEN  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2004-01-20  
Effective Receipt Date: 2004-04-22  
Submission Type: Information Disclosure  
Statement  
Filing Type:  
Confirmation number: 8790  
Attorney Docket Number: AMAT5735C1  
Total Fees Authorized: 180.0  
Payment Category: Deposit Account  
Deposit Account Number: 200782  
Deposit Account Name: BRIAN K. HRNA  
Access Code: \*\*\*\*  
RAM Payment Status: RAM success  
RAM User ID: EFSPROD  
RAM Accounting Date: 2004-04-22  
RAM Sequence Number: 34




Digital Certificate Holder: cn=Brian K. Hrna,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US  
Certificate Message Digest: 18f9e7968ceb74a5d3dd97d5a258f58393021419



TRANSMITTAL

Electronic Version v1.1  
Stylesheet Version v1.1.0

Title of Invention	SOLVENT FREE PHOTORESIST STRIP AND RESIDUE REMOVAL PROCESSING FOR POST ETCHING OF LOW-K FILMS															
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<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>																
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>BRIAN K. HRNA Registered Number: 41,852</td><td>[BRIAN K. HRNA]</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	BRIAN K. HRNA Registered Number: 41,852	[BRIAN K. HRNA]	Attorney								
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Comments

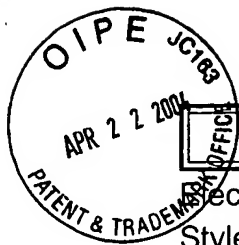


## FEE TRANSMITTAL


Electronic Version v08

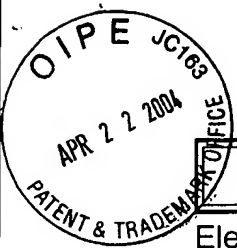
Stylesheet Version v08.0

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<b>TOTAL FEE AUTHORIZED \$180</b>											
Patent fees are subject to annual revisions on or about October 1st of each year.											
<b>BASIC FILING FEE</b>											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
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Submission Of Information Disclosure Stmt Fee	1806	180	180								
<b>AUTHORIZED BILLING INFORMATION</b>											
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:											
Deposit account number: 200782											
Access Code ****											
Deposit name: MOSER PATTERSON SHERIDAN											
Deposit authorized name: BRIAN K. HRNA											
Signature: /BRIAN K. HRNA/											
Date (YYYYMMDD): 2004-04-22											

**FEE TRANSMITTAL**

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## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of  
Invention

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Application Number: 10/761122



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Search string: (6214728 or 6130166 or 6124213 or 6074569  
or 6062237 or 6046115 or 6043004 or 6037255  
or 6030901 or 6024045 or 5811358 or 5681780  
or 5660682 or 4357203 or 4028155 ).pn.

### US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	6214728	2001-04-10	CHAN, ET AL.			
	2	6130166	2001-10-10	YEH			
	3	6124213	2000-09-26	USAMI, ET AL.			
	4	6074569	2000-06-13	KIZILOGLU, ET AL.			
	5	6062237	2000-05-16	BROWN, ET AL.			
	6	6046115	2000-04-04	MOLLOY, ET AL.			
	7	6043004	2000-03-28	KURIMOTO			
	8	6037255	2000-03-14	HUSSEIN, ET AL.			
	9	6030901	2000-02-29	HOPPER, ET AL.			
	10	6024045	2000-02-15	KIKUCHI, ET AL.			
	11	5811358	1998-09-22	TSENG, ET AL.			
	12	5681780	1997-10-28	MIHARA, ET AL.			
	13	5660682	1997-08-27	ZHAO, ET AL.			
	14	4357203	1982-11-02	ZELEZ			
	15	4028155	1977-06-07	JACOB			

Signature

Examiner Name	Date